

ELECTRONIC DEVICE AND MANUFACTURING METHOD THEREOF

ABSTRACT OF THE DISCLOSURE

An electronic device, including an active device substrate, an insulation film, a vertical
5 wire, and an anisotropic conductive adhesive, is provided. The active device substrate includes
a substrate, a first wire, and a second wire. The first wire is configured on a first surface of the
substrate, the second wire is configured on a second surface of the substrate, and a side surface
connects the first surface to the second surface that is opposite to the first surface. The
insulation film is configured on the side surface of the substrate. The vertical wire is
10 configured on a surface of the insulation film and is located between the insulation film and the
side surface of the substrate. The anisotropic conductive adhesive is configured between the
vertical wire and the side surface of the substrate and electrically connects the vertical wire to
the first wire and the second wire.

15 Fig. 9